

APPLICATION DATA SHEET**Inventor Information**

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Application Information

Title : LEADFRAME AND METHOD FOR REDUCING MOLD
COMPOUND ADHESION PROBLEMS
Total Drawing Sheets : 5
Formal Drawings : YES
Application Type : Utility
Attorney Docket Number : 501062.01
Assigned : Yes (Large Entity)

Representative Information

Representative Customer No. : 27,076

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TOTAL: 354,660